

Features

$V_{(BR)DSS}$	$R_{DS(ON)} \text{ max}$	$I_D \text{ max}$ $T_A = +25^\circ\text{C}$
-20V	150mΩ @ $V_{GS} = -4.5\text{V}$	-1.9A
	200mΩ @ $V_{GS} = -2.5\text{V}$	-1.7A

Application

- Notebook
- Load Switch
- Networking
- Hand-held Instruments

Package and Pin Configuration



Maximum Ratings (@ $T_A = +25^\circ\text{C}$ unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	-20	V
Gate-Source Voltage			V_{GSS}	± 12	V
Continuous Drain Current (Note 5) $V_{GS} = -4.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	I_D	-1.9 -1.5	A
Continuous Drain Current (Note 5) $V_{GS} = -4.5\text{V}$	$t \leq 5\text{s}$	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	I_D	-2.1 -1.65	A
Continuous Drain Current (Note 5) $V_{GS} = -2.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	I_D	-1.7 -1.3	A
Pulsed Drain Current		$t_p = 10\mu\text{s}$	I_{DM}	-4.0	A

Thermal Characteristics

Characteristic	Symbol	Value	Units
Power Dissipation (Note 5)	P_D	0.85	W
Thermal Resistance, Junction to Ambient @ $T_A = +25^\circ\text{C}$ (Note 5)	$R_{\theta JA}$	146	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$ unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV_{DSS}	-20	—	—	V	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_D = -250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = +25^\circ\text{C}$ $T_J = +125^\circ\text{C}$	$\text{I}_{\text{DS}0}$	—	—	-1.0 -5.0	μA	$\text{V}_{\text{DS}} = -20\text{V}, \text{V}_{\text{GS}} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$\text{V}_{\text{GS}} = \pm 12\text{V}, \text{V}_{\text{DS}} = 0\text{V}$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	-0.45	—	-1.0	V	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{I}_D = -250\mu\text{A}$
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(on)}}$	—	92 134 180	150 200 240	$\text{m}\Omega$	$\text{V}_{\text{GS}} = -4.5\text{V}, \text{I}_D = -950\text{mA}$ $\text{V}_{\text{GS}} = -2.5\text{V}, \text{I}_D = -670\text{mA}$ $\text{V}_{\text{GS}} = -1.8\text{V}, \text{I}_D = -200\text{mA}$
Forward Transconductance	g_{FS}	—	3.1	—	S	$\text{V}_{\text{DS}} = -10\text{V}, \text{I}_D = -810\text{mA}$
Diode Forward Voltage (Note 6)	V_{SD}	—	—	-0.9	V	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_S = -360\text{mA}$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	—	320	—	pF	$\text{V}_{\text{DS}} = -16\text{V}, \text{V}_{\text{GS}} = 0\text{V}$
Output Capacitance	C_{oss}	—	80	—	pF	$f = 1.0\text{MHz}$
Reverse Transfer Capacitance	C_{rss}	—	60	—	pF	



TECH PUBLIC
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NTZS3151PT1G-TP

P-Channel Enhancement Mode MOSFET

Typical Electrical and Thermal Characteristics

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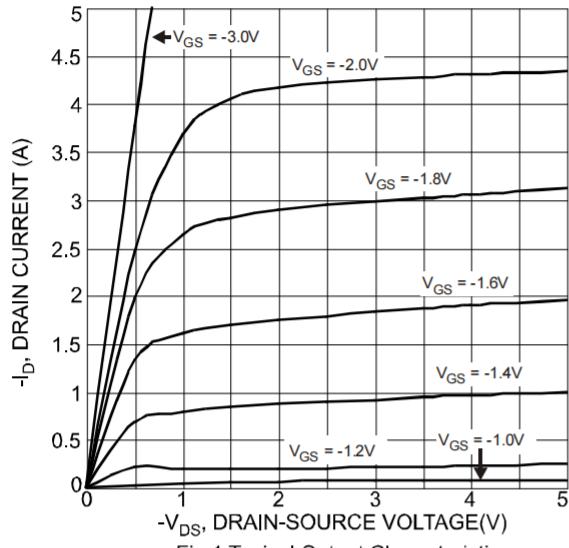


Fig. 1 Typical Output Characteristics

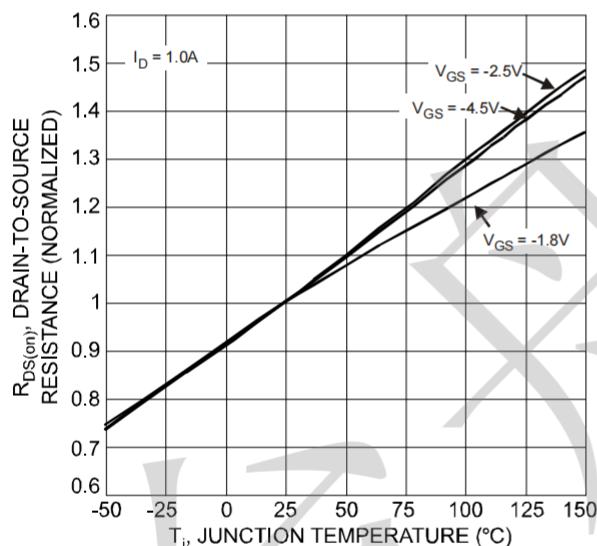


Fig. 3 On-Resistance Variation with Temperature

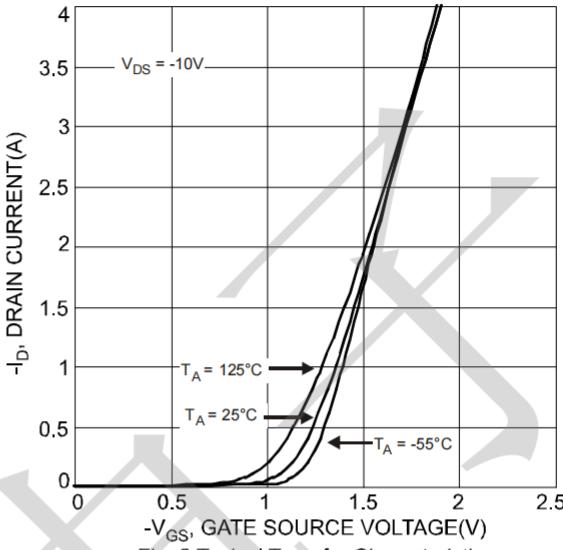


Fig. 2 Typical Transfer Characteristics

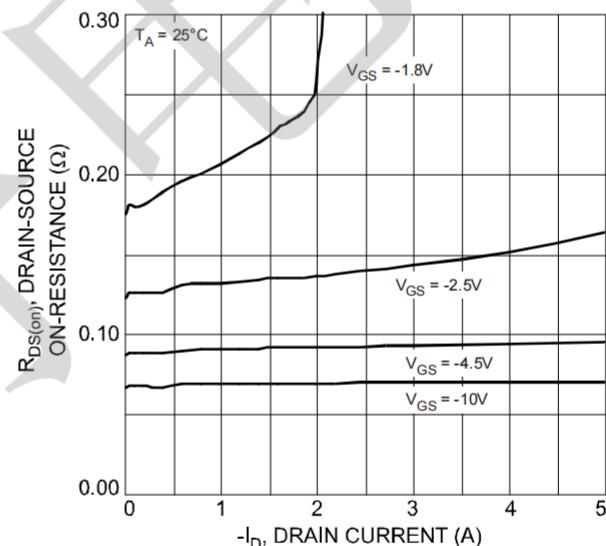


Fig. 4 On-Resistance vs. Drain Current and Gate Voltage

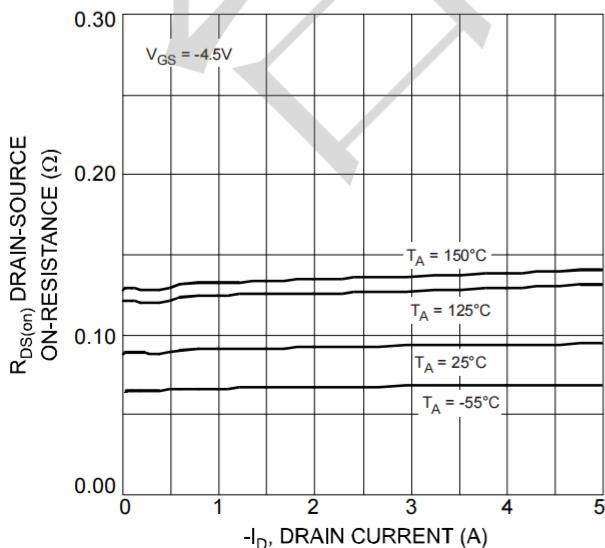


Fig. 5 Drain-Source On-Resistance vs. Drain Current and Temperature

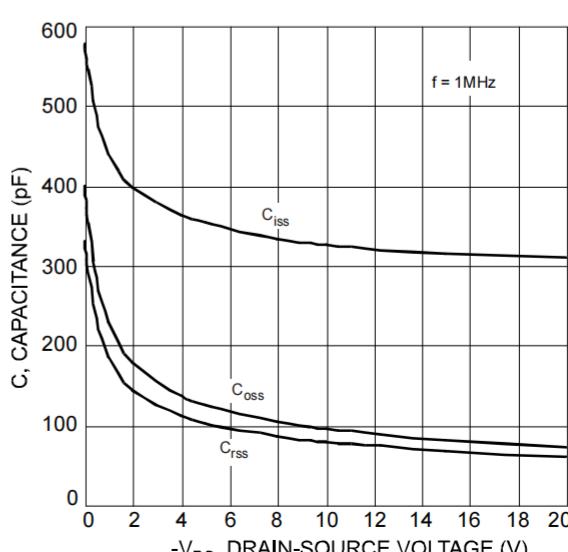


Fig. 6 Typical Capacitance

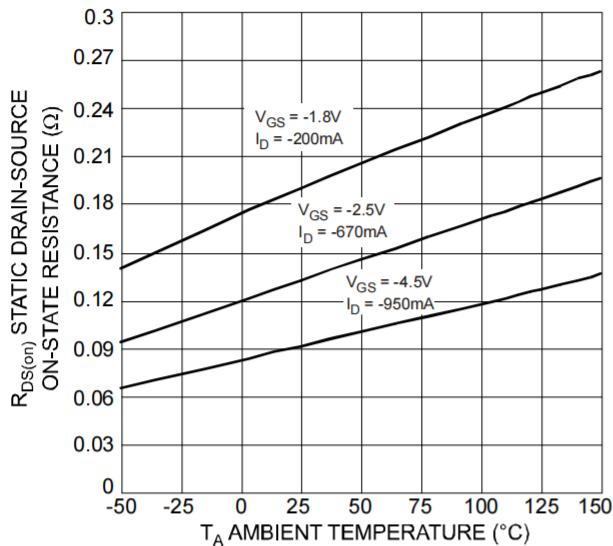


Fig. 7 Static Drain-Source On-State Resistance vs. Ambient Temperature

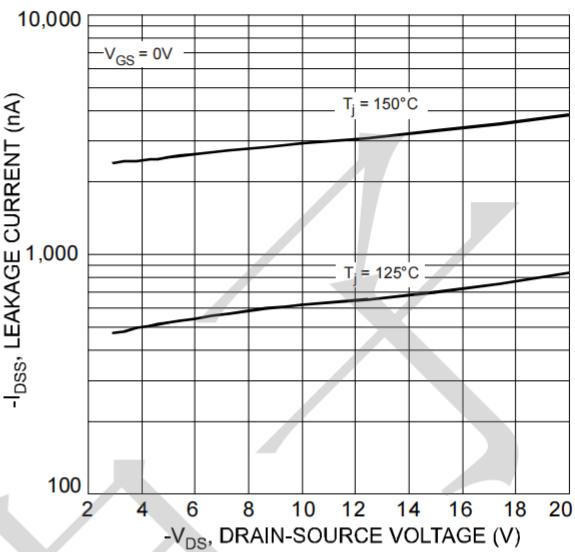


Fig. 8 Drain-Source Leakage Current vs. Voltage

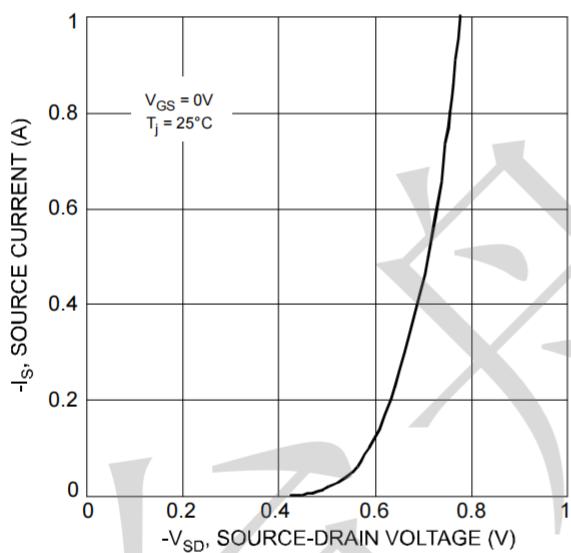
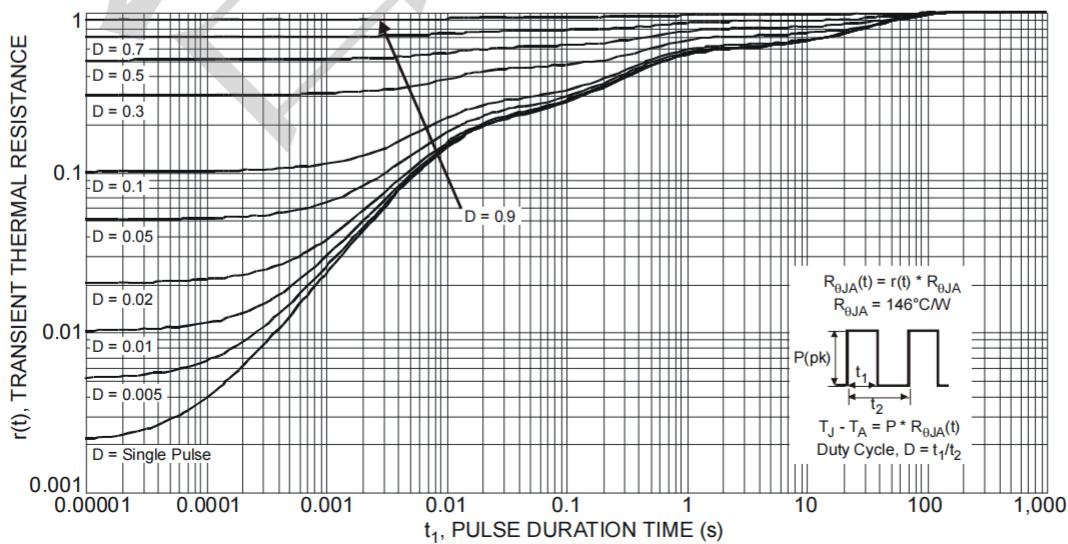
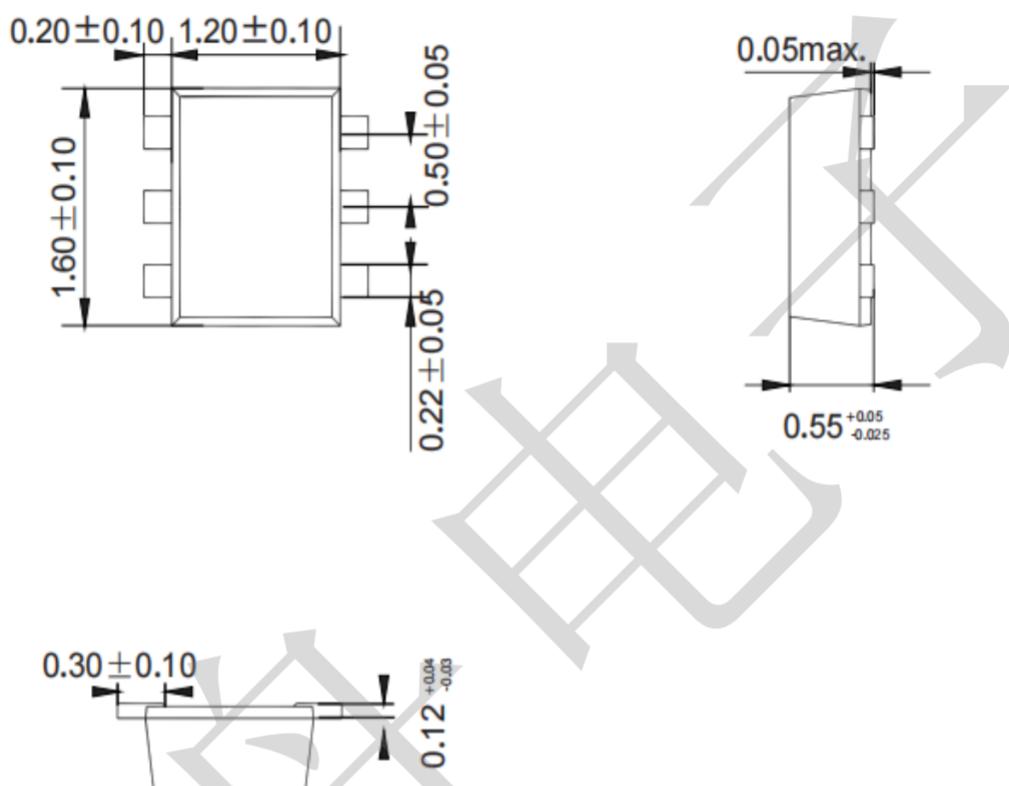


Fig. 9 Diode Forward Voltage vs. Current



Package Outline Dimensions (unit:mm)

SOT-563



Mounting Pad Layout (unit: mm)

